

PXP1500-100QS 100 V, P-channel Trench MOSFET 20 November 2021

**Product data sheet** 

### 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002-2) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 2. Features and benefits

- Trench MOSFET technology •
- MLPAK33 package (3.3 x 3.3 mm footprint)
- Low thermal resistance
- Low 0.8 mm profile •

### 3. Applications

• Active clamp circuits

### 4. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-	-100	V
V <sub>GS</sub>	gate-source voltage			-20	-	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C	[1]	-	-	-0.7	А
Static chara	acteristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = -10 V; I <sub>D</sub> = -0.7 A; T <sub>j</sub> = 25 °C		-	930	1500	mΩ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



# 5. Pinning information

Table 2	. Pinning info	ormation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	1 2 3 4	
2	S	source		D
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain		S
7	D	drain		017aaa094
8	D	drain	MLPAK33 (SOT8002-2)	

# 6. Ordering information

Table 3. Ordering information							
Type number	Package						
	Name	Description	Version				
PXP1500-100QS		plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body	SOT8002-2				

# 7. Marking

Table 4. Marking codes	
Type number	Marking code
PXP1500-100QS	9ам

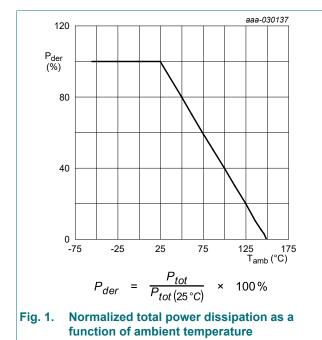
## 8. Limiting values

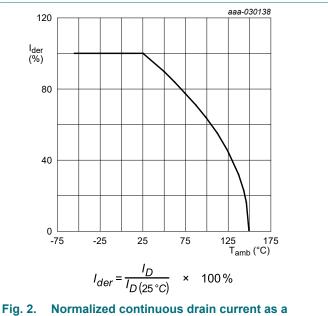
#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-100	V
V <sub>GS</sub>	gate-source voltage	1		-20	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C	[1]	-	-0.7	А
		V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 100 °C	[1]	-	-0.4	А
		V <sub>GS</sub> = -10 V; T <sub>sp</sub> = 25 °C		-	-1.4	А
I <sub>DM</sub>	peak drain current	$T_{amb}$ = 25 °C; single pulse; $t_p \le 10 \ \mu s$		-	-3	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[1]	-	1.4	W
		T <sub>sp</sub> = 25 °C		-	6.1	W
Tj	junction temperature			-55	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C
Source-drain	n diode				-	
ls	source current	T <sub>amb</sub> = 25 °C	[1]	-	-0.66	А
Avalanche ru	uggedness				·	
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	T <sub>j(init)</sub> = 25 °C; I <sub>D</sub> = -0.6 A; DUT in avalanche (unclamped)		-	7	mJ

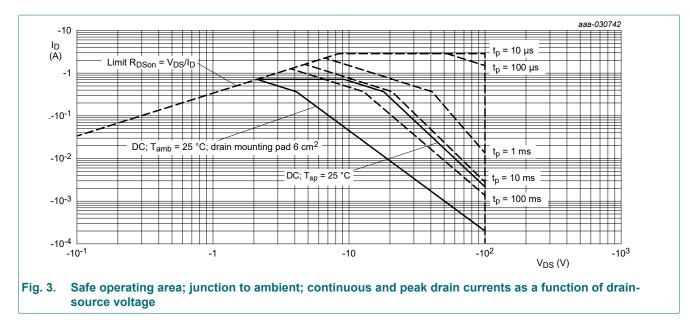
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.







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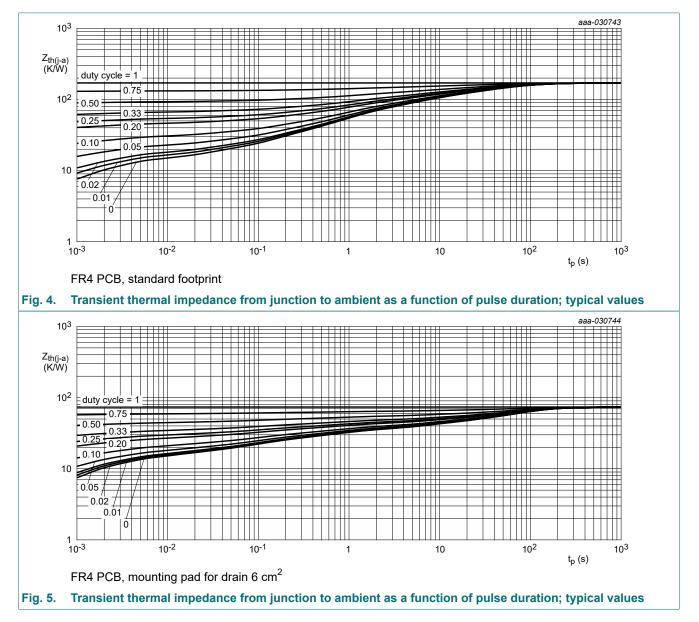


## 9. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub> thermal resistance from junction to ambient	thermal resistance from	in free air	[1]	-	170	205	K/W
		[2]	-	75	90	K/W	
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point			-	17.2	20.5	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

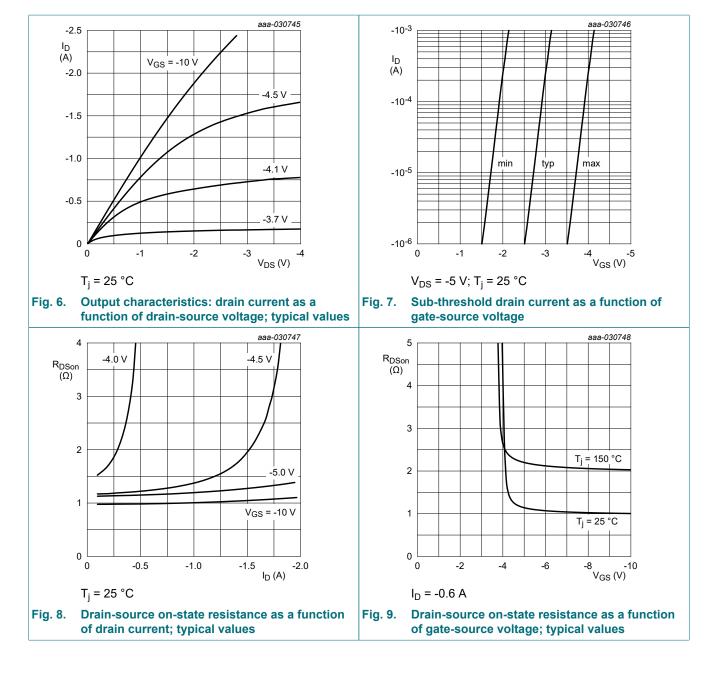
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



# **10. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-100	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	$I_D$ = -250 µA; $V_{DS}$ = $V_{GS}$ ; $T_j$ = 25 °C	-2	-3	-4	V
I <sub>DSS</sub>	drain leakage current	$V_{GS} = 0 V; V_{DS} = -100 V; T_j = 25 °C$	-	-	-1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-100	nA
		V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
R <sub>DSon</sub>	drain-source on-state	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -0.7 A; T <sub>j</sub> = 25 °C	-	930	1500	mΩ
	resistance	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -0.7 A; T <sub>j</sub> = 150 °C	-	2000	3165	mΩ
		V <sub>GS</sub> = -6 V; I <sub>D</sub> = -0.6 A; T <sub>j</sub> = 25 °C	-	1000	1700	mΩ
9fs	forward transconductance	V <sub>DS</sub> = -5 V; I <sub>D</sub> = -0.7 A; T <sub>j</sub> = 25 °C	-	1.6	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz	-	26	-	Ω
Dynamic ch	aracteristics		I			
Q <sub>G(tot)</sub>	total gate charge	$V_{DS}$ = -50 V; I <sub>D</sub> = -0.6 A; V <sub>GS</sub> = -10 V; T <sub>j</sub> = 25 °C	-	3.1	4.5	nC
		$V_{DS}$ = -50 V; I <sub>D</sub> = -0.6 A; V <sub>GS</sub> = -6 V;	-	2.1	3.1	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C	-	0.6	-	nC
Q <sub>GD</sub>	gate-drain charge		-	0.9	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -50 V; f = 1 MHz; V <sub>GS</sub> = 0 V;	-	159	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C	-	8	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	4.5	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = -50 V; I <sub>D</sub> = -0.6 A; V <sub>GS</sub> = -6 V;	-	5	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C$	-	17	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	5	-	ns
t <sub>f</sub>	fall time		-	12	-	ns
Source-drai	n diode	· · · · · ·				
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -0.7 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-0.8	-1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = -0.6 A; dI <sub>S</sub> /dt = -100 A/µs;	-	24	-	ns
Q <sub>r</sub>	recovered charge	V <sub>GS</sub> = -6 V; V <sub>DS</sub> = -40 V; T <sub>j</sub> = 25 °C	-	20	-	nC

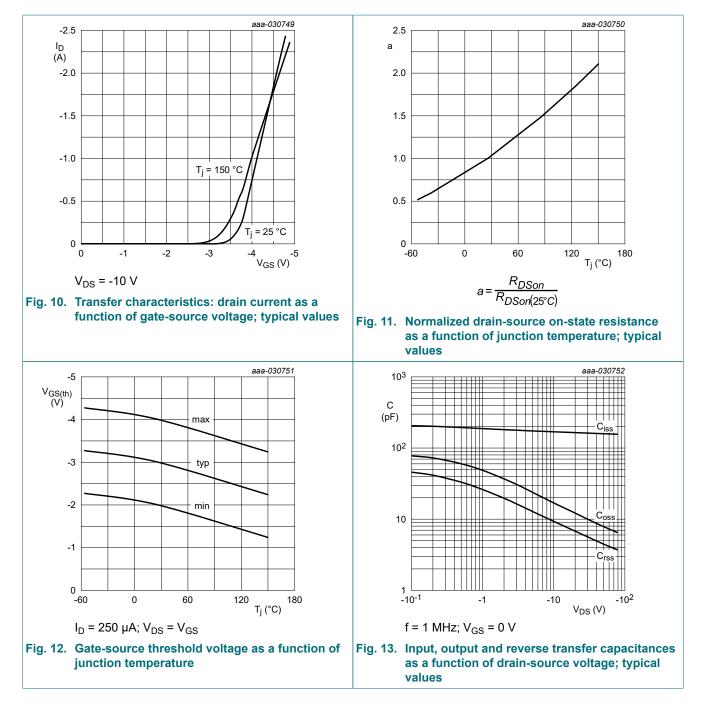
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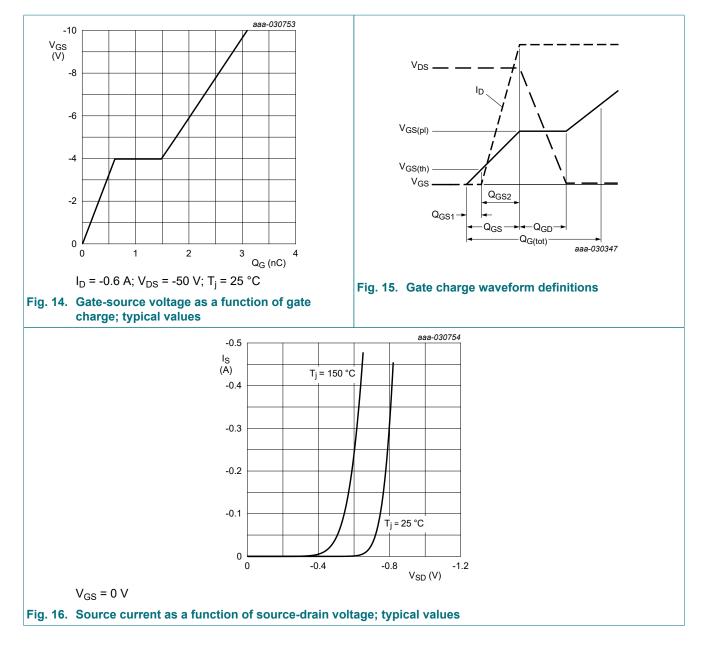
PXP1500-100QS

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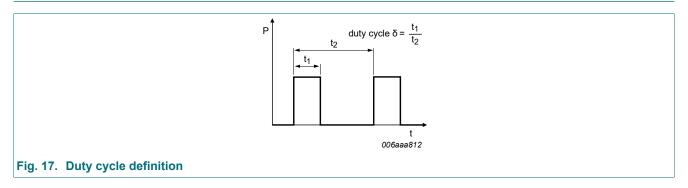
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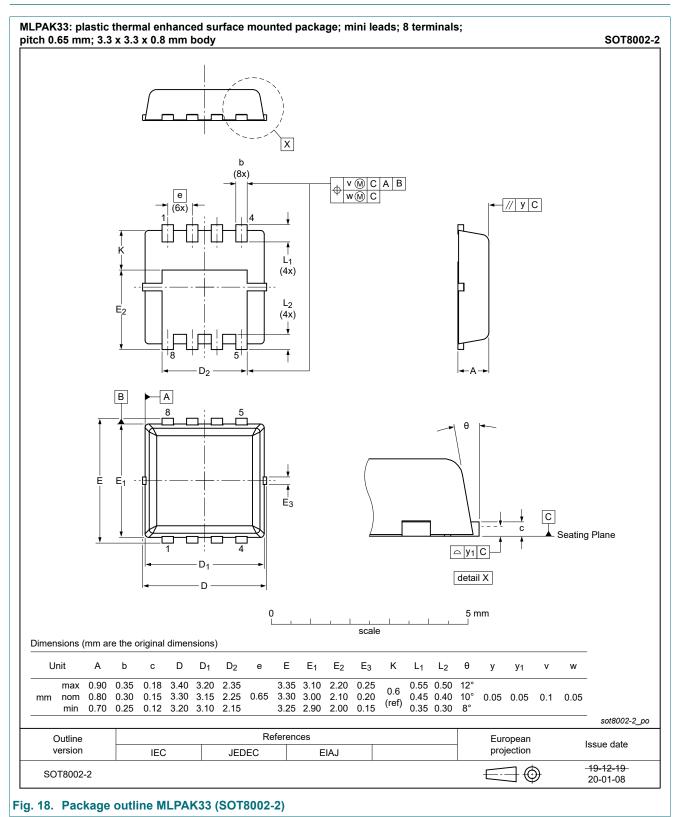
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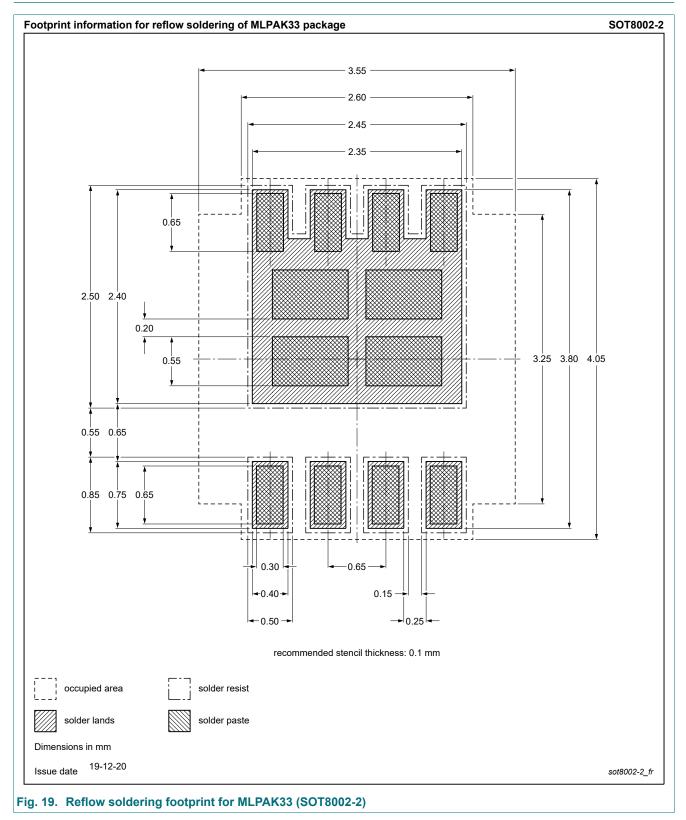
## **11. Test information**



## 12. Package outline



## 13. Soldering



# 14. Revision history

Table 8. Revision history							
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes			
PXP1500-100QS v.2	20211120	Product data sheet	-	PXP1500-100QS v.1			
Modifications:	Chapter "Limiting values": P <sub>tot</sub> corrected, now matching the data in chapter "Thermal characteristics"						
PXP1500-100QS v.1	20200507	Product data sheet	-	-			

# 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

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